

## General info document for PCB manufacturing

No.	Item Name	File Name				Info / Remarks / Notes
	<b>BOARD</b>					
1	Board Name / Number	P1_V3_PCB				-
2	Revision Date	13.12.2025				-
3	Board Size	40 x 40 mm <sup>2</sup>				-
4	Board Quantity	1				-
5	Material / Dielectric Type	FR-4				-
6	Board Thickness	1.6 mm				-
7	Copper Thickness	18 µm				-
	<b>LAYERS</b>					
8	Number of Electrical Layers	2				-
9	Copper Layer TOP	TOP.art				-
10	Copper Layer BOTTOM	BOTTOM.art				-
11	Copper GND Plane	-				-
12	Copper PWR Plane	-				-
13	Copper INNER 1	-				-
14	Copper INNER 2	-				-
15	Solder Mask TOP	SMTOP.art				-
16	Solder Mask BOTTOM	SMBOT.art				-
17	Solder Paste TOP	SPTOP.art				-
18	Solder Paste BOTTOM	-				-
19	Peelable Mask TOP	-				-
20	Peelable Mask BOTTOM	-				-
21	Silk Screen TOP	SSTOP.art				-
22	Silk Screen BOTTOM	-				-
23	Board Outline	BO.art				-
24	Fabrication Drawing	FAB.art				-
	<b>MILLING &amp; DRILLING</b>					
25	Mill Drawing	-				-
26	Drill Drawing	-				-
27	N.C. Drill (for both PH & NPH)	DRILL.drl				-
28	N.C. Drill / Plated Holes (PH)	25				-
29	N.C. Drill / Non-Plated Holes (PH)	25				-
	<b>FINISHING</b>					
30	Panelisation	-				-
31	Electrical Test	-				-
32	Copper Finishing	x	HASL		OSP	ENIG
33	Board Outline Machining		Routing	Milling	x	V-Cutting
34	Final remarks		-			-